

ABSTRACT

5 Composition for metal electroplating comprising an additive for bottom-up filling of through silicon
vias and interconnect features

10 A composition comprising a source of metal ions and at least one polyaminoamide, said poly-
aminoamide comprising amide and amine functional groups in the polymeric backbone and ar-
omatic moieties attached to or located within said polymeric backbone.

(No suitable figure)